

SEMI Standards Staff Report

September 18, 2019 v0.3

SEMI Japan



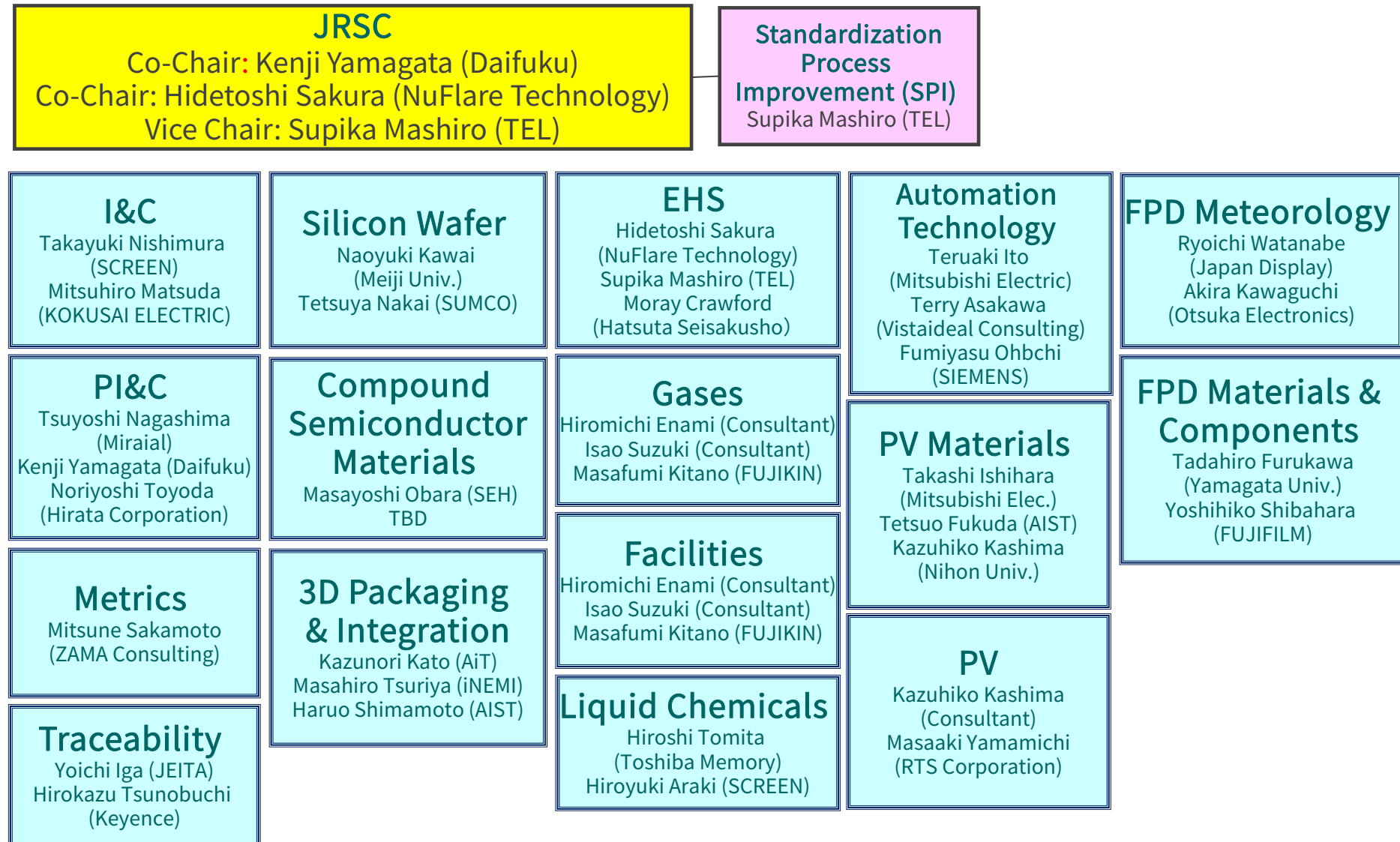
Contents

- JRSC Update/Organization
- SEMI通信 / SEMI Japan e-mail newsletter
- SEMI Global Calendar of Events
- Global Standards Meeting Schedule
- 2019 Critical Dates for SEMI Standards Ballots
- A&R Ballot Review
- SEMI Standards Publications
- Regulations and Procedure Manual
- Staff Assignment

JRSC Update

- 会議
 - 前回会議：8月30日（金）
 - 次回会議：12月10日（火） 15:00-17:00
- 2019年度日本地区委員会プランニング会議
 - 2019年8月30日（金）午後
 - SEMIジャパン会議室
 - トピックス
 - 実行手引き（Execution Guide）のワーク
 - Connected@SEMIを使ってみるセッション
- 中国に化合物半導体材料委員会が設立
 - SEMICON West関連会議にて承認
- Membership update
 - 新共同議長（2020年より）：西村氏（SCREENセミコンダクターソリューションズ）
 - 現共同議長山形氏（ダイフク）2019年末任期満了のため

JRSC Organization Chart



SEMI通信 (2019年)

テーマ募集中!!

- 2019_01_SEMIジャパン・スタンダード賞、2018年度は2名が受賞
✓号名の付け方が変わりました。
- 2019_03 (2月発信) PLP樹脂封止装置の特徴と課題について
- 2019_04 (3月発信) 表面光起電力法によるシリコンウェーハの少数キャリア拡散長測定のための試料の前処理法の紹介 (SEMI M88)
- 2019_05 (4月発信) ガス検知の活動への参加について 「SEMI S6半導体製造装置の排気換気に関する環境、健康、安全のためのガイドライン」改訂活動
- 2019_06 (5月発信) 装置データ収集 (EDA) スタンダード Freeze Version 3 を検討中
- 2019_07 (6月発信) 2019年春、トレーサビリティ委員会に設立した2つのタスクフォースの紹介
- 2019_08 (7月発信) FO-PLPに関する標準化活動の進捗
- 2019_09 (8月発信) スタンダード特集号 1000規格突破記念
- 2019_10 (9月発信) F-GEM (Flow-shop Generic Equipment Model) Task ForceをAutomation Technology委員会下に新設

SEMI通信

2019年9月号詳細

- 標準規格こそSEMIの最大の業界貢献 その成り立ちとこれから
 - <http://www1.semi.org/jp/node/85166/>
- 記念すべき1000thスタンダードはエナジェティックマテリアルのガイドライン
 - <http://www1.semi.org/jp/node/85156/>
 - （HQマーケティング担当者による記事の翻訳）
- PLP Panel FOUPの標準化活動の現在
 - <http://www1.semi.org/jp/node/85151/>
- SMT組立ラインをよりスマートにするスタンダード群、いよいよ実装フェーズへ
 - <http://www1.semi.org/jp/node/85146/>

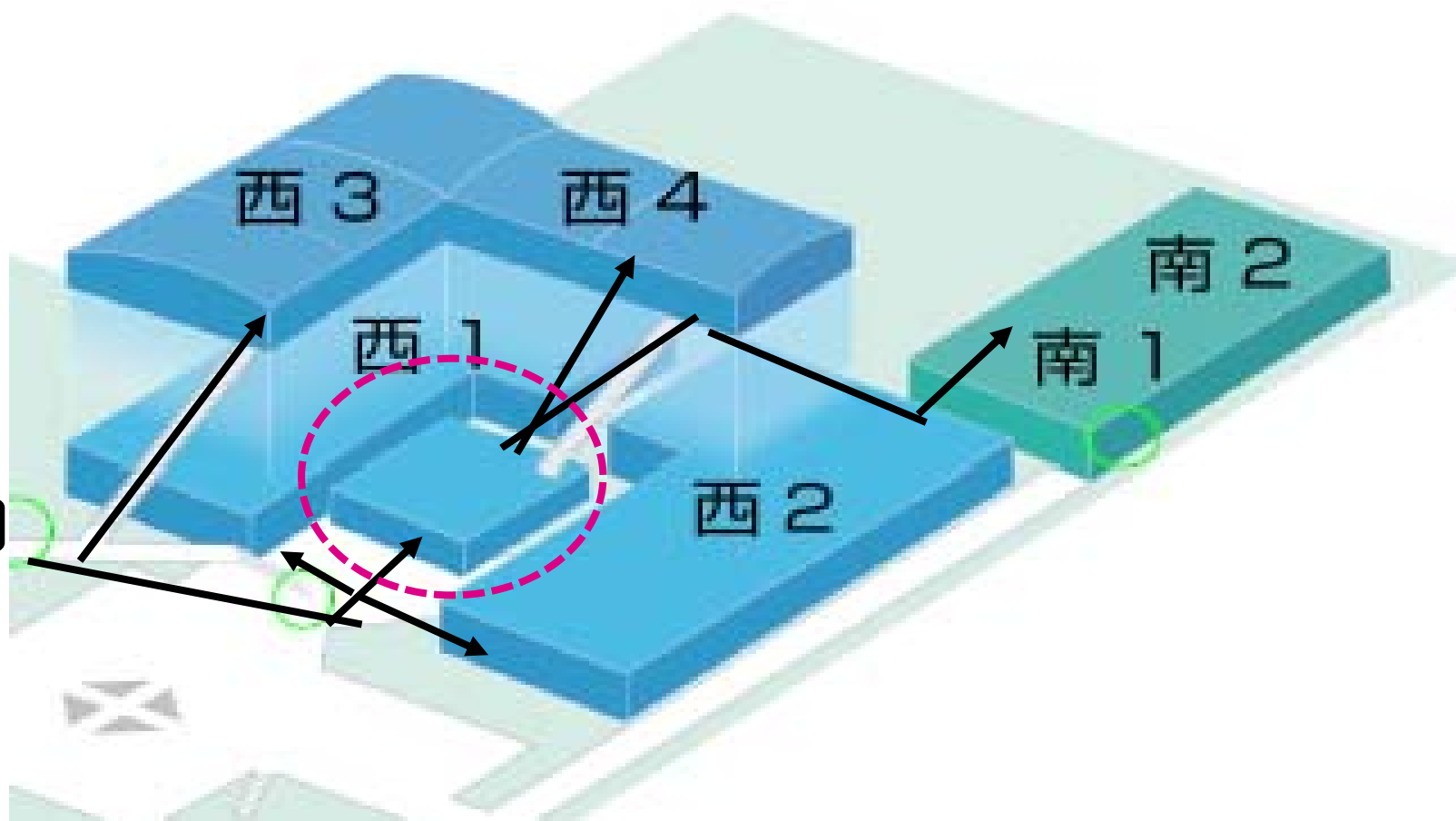
SEMI Global 2019 Calendar of Events

Event Name	Event Details
SEMICON[®] KOREA	Jan. 23 -25, 2019 Seoul. South Korea
SEMICON[®] CHINA	Mar 20-22, 2019 Shanghai, China
SEMICON[®] SOUTHEAST ASIA	May 7-9, 2019 Kuala Lumpur, Malaysia
SEMICON[®] WEST	July 9-11, 2019 San Francisco, California
SEMICON[®] TAIWAN	Sept 18-20, 2019 Taipei, Taiwan
SEMICON[®] EUROPA	Nov 12-15, 2019 Munich, Germany
SEMICON[®] JAPAN	Dec 11-13, 2019 Tokyo, Japan

**SEMICON[®]
JAPAN**

2019年12月11日(水)～13日(金)
東京ビッグサイト
西・南展示棟／会議棟

登録所



展示	半導体 製造装置・部品・材料		
	SMART APPLICATIONS ZONE	SMART TRANSPORTATION	
		表 面 イ ン フ ォ ー メ ー シ ョ ン パ ビ リ オ ン	SMART MANUFACTURING
		九州 パビリオン	東北 パビリオン

SEMI プレジ デント レセプ ション	Happy Hour		Supplier Search Progra m
GET TOGETHE R		オーブ ニング セレモ ニー	中国 デリゲ ーション プログラ ム
ネット ワーキング		スピー カーズ ランチョ ン	

セミナー		SuperTHEATER
TechSTAGE	STS	
SEMI MARKET	SEMI TUTORIAL	出展者 セミナー

SEMICON[®] JAPAN

SMART WORKFORCE		THE高 専	TECH CAMP
未来 COLLEG E	未来 プログラ ム		アカデミ ア

SEMI IS MORE	特別 企画展 示	SEMI IS MORE
BCPArea Business Continuity Plan		

スタンダード	
	
SEMI スタン ダード フレンド シップ パーティ	1000 SEMI STANDARDS & COUNTING
SEMI スタン ダード 会議	SEMI スタン ダード ワーク ショップ



がかわります

1セッション
4,000円
(早割会員価格)

日時：2019年12月11日（水）～13日（金） ①10:30-12:30 ②14:00-16:00

会場：東京ビッグサイト会議棟101・102

セッションラインナップ：

- ・ 特別セッション：次世代デバイス
- ・ 先端材料・分析セッション - In-line 分析最前線
- ・ 先端デバイス・プロセス
- ・ 先端リソグラフィー - 先端リソグラフィー技術の最新動向
- ・ パッケージング - 5G革命を実現するパッケージ・実装技術の課題と展望
- ・ テスト - スマート社会の基盤を支えるテスト技術
- ・ パワーデバイス - 新材料パワーデバイスの技術動向最前線
- ・ MEMS・SMARTセンシングデバイス - 次世代アプリケーションをリードするMEMS

Standards Meeting (TC Chapter/FS party/Workshop)

- JRSC 12/10 15:30-18:00
@SEMI Japan (Invitation Only)
 - LC TC 12/11 13:00-15:00
 - PI&C 12/11 15:00-17:00
 - ISC 12/12 08:30-11:30 (Invitation Only)
 - Traceability 12/12 09:00-11:00
 - Metris 12/12 15:30-17:00
 - Silicon Wafer 12/12 13:00-17:00
 - Friendship Party 12/12 17:30-19:00
 - EHS 12/13 13:00-16:00
 - I&C 12/13 13:00-17:00
-
- 3DSP&I WS 12/11 10:20-12:00
 - Traceability WS 12/12 12:50-14:30

Global Standards Meeting Schedule

<https://www.semi.org/en/collaborate/standards>

- August 29, 2019
EHS Japan TC Chapter
SEMI Japan Office
- September 6, 2019
FPD - Materials & Components Japan TC Chapter
SEMI Japan Office
- September 20, 2019
PI&C Japan TC Chapter
SEMI Japan Office
- September 26, 2019
Information & Control Japan TC Chapter
SEMI Japan Office
- September 26, 2019
Compound Semiconductor Materials China TC Chapter
SEMI China Office
- September 27, 2019
HB-LED China TC Chapter
SEMI China Office
- September 27, 2019
Information & Control Taiwan TC Chapter
SEMI Taiwan Office.
- October 2, 2019
Automation Technology Japan TC Chapters
SEMI Japan Office
- October 4, 2019
Gases & Facilities Japan TC Chapters Joint Meeting
SEMI Japan Office
- October 11, 2019
3D Packaging & Integration Japan TC Chapter Meeting
SEMI Japan Office
- October 16, 2019
EHS Taiwan TC Chapter
SEMI Taiwan Office
- October 25, 2019
PV & PV Materials China TC Chapters Joint Meeting
Beijing, China
- October 30, 2019
Automation Technology Taiwan TC Chapter
SEMI Taiwan Office
- October (tentative), 2019
PV Taiwan TC Chapter
SEMI Taiwan Office
- November 4 – November 7, 2019
North America Standards Fall 2019 Meetings
Milpitas, California, United States
- November 5, 2019
PV & PV Materials Japan TC Chapters Joint Meeting
SEMI Japan Office
- November 12– November 15, 2019
Europe Standards Fall 2019 Meetings
Milpitas, California, United States
- November, 2019
FPD – Metrology Japan TC Chapter
SEMI Japan Office
- December 10 – December 13, 2019
SEMICON Japan Standards Meetings
Tokyo Big Sight, Tokyo, Japan
- February 7, 2020
FPD - Metrology Taiwan TC Chapter
ITRI Office

Upcoming North America STD Meetings

Event Name	Date / Venue
NA Standards Fall 2019 Meetings	November 4-7, 2019 SEMI HQ in Milpitas, California
NA Standards Spring 2020 Meetings	March 30- April 2, 2020 (tentative) SEMI HQ in Milpitas, California

Seminar: Tutorials & STEP

- SEMI SMT-ELS Workshop on October 8, 2019
- STEP/SEMI S2 on November 1, 2019

2019 Critical Dates for SEMI Standards Ballots





2019	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 2	Feb 1	Feb 15	Mar 18
Cycle 3	Mar 12	Mar 26	Apr 25
Cycle 4	Apr 16	Apr 30	May 30
Cycle 5	May 10	May 24	Jun 24
Cycle 6	July 19	July 31	Aug 30
Cycle 7	Aug 22	Sept 4	Oct 4
Cycle 8	Oct 11	Oct 25	Nov 25
Cycle 9	Nov 14	Nov 26	Dec 26

https://www.semi.org/en/standards/Critical_Dates

2020 Critical Dates for SEMI Standards Ballots (tentative)

2020	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 1	Jan 6	Jan 15	Feb 14
Cycle 2	Jan 30	Feb 11	Mar 12
Cycle 3	Mar 11	Mar 25	Apr 24
Cycle 4	Apr 16	Apr 29	May 29
Cycle 5	May 18	June 1	July 1
Cycle 6	Aug 3	Aug 17	Sept 16
Cycle 7	Sept 1	Sept 15	Oct 15
Cycle 8	Oct 9	Oct 23	Nov 23
Cycle 9	Nov 10	Nov 23	Dec 23

A&R Ballot Review (2019)

A&R Cycle	Result	Notes
January 2019	 ISCA&RSCWebJa 19VotingSummar	All passed
May 2019	 Adobe Acrobat Document	All Passed
June 2019	 2019_June_A&R	Doc. 5661D and 6497 failed.
August 2019	 2019_Aug_A&R	All Passed

SEMI Standards Publications (2019)

Cycle	New	Revised	Reapproved	Withdrawn
January 2019	2	0	0	0
February 2019	1	3	4	0
March 2019	1	5	6	0
April 2019	1	4	6	0
May 2019	0	16	5	0
June 2019	1	5	5	0
July 2019	2	3	0	0

- Total SEMI Standards in portfolio: 1,007
 - Includes 268 Inactive Standards

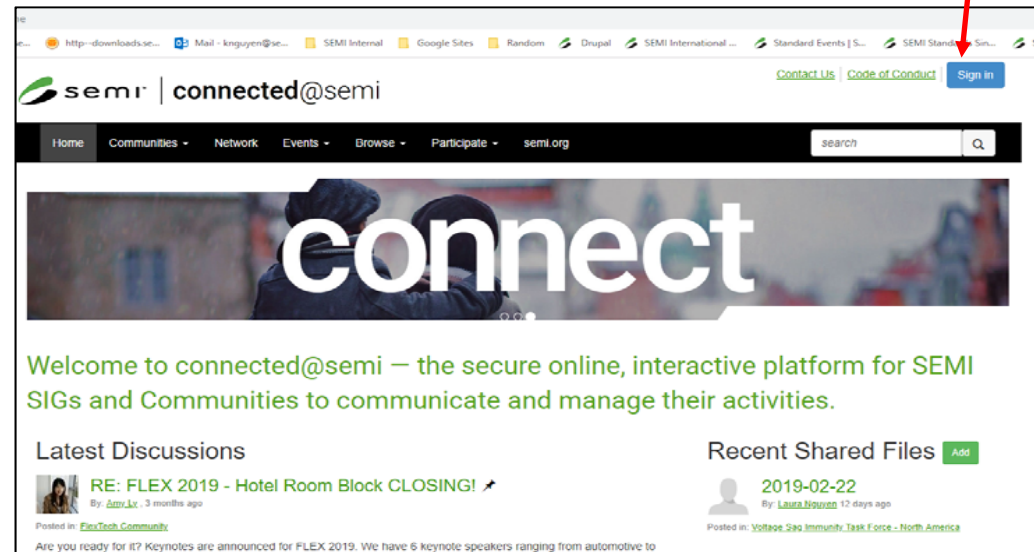
SEMI Standards Publications (2019)

New Standards

Cycle	Designation	Title	Committee	Region
June 2019	SEMI 3D19	Test Method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling	3D Packaging & Integration	JA
July 2019	SEMI 3D20	Specification for Panel Characteristics for Panel Level Packaging (PLP) Applications	3D Packaging & Integration	NA
July 2019	SEMI S30	Safety Guideline for Use of Energetic Materials in Semiconductor R&D and Manufacturing Processes	EHS	NA
Aug 2019	SEMI A3	Specification for Printed Circuit Board Equipment Communication Interfaces (PCBEI)	Automation Technology	TW
Sept 2019	SEMI E177	Specification for TEM Lamella Carrier Used in Electron Microscopy Workflows	Physical Interfaces & Carriers	NA

connected@SEMI

- Web link - <https://connect.semi.org>
 - Login using Standards account (username and password)
- Program Member
 - Join any task forces
 - Post discussion thread
- TF Leader/Community Admin
 - Add member
 - Upload meeting minutes
 - Communicate TF members
 - Contact your staff if a TF Site is desired
- Details
 - www.semi.org/standards → Committee Info → Collaboration Community

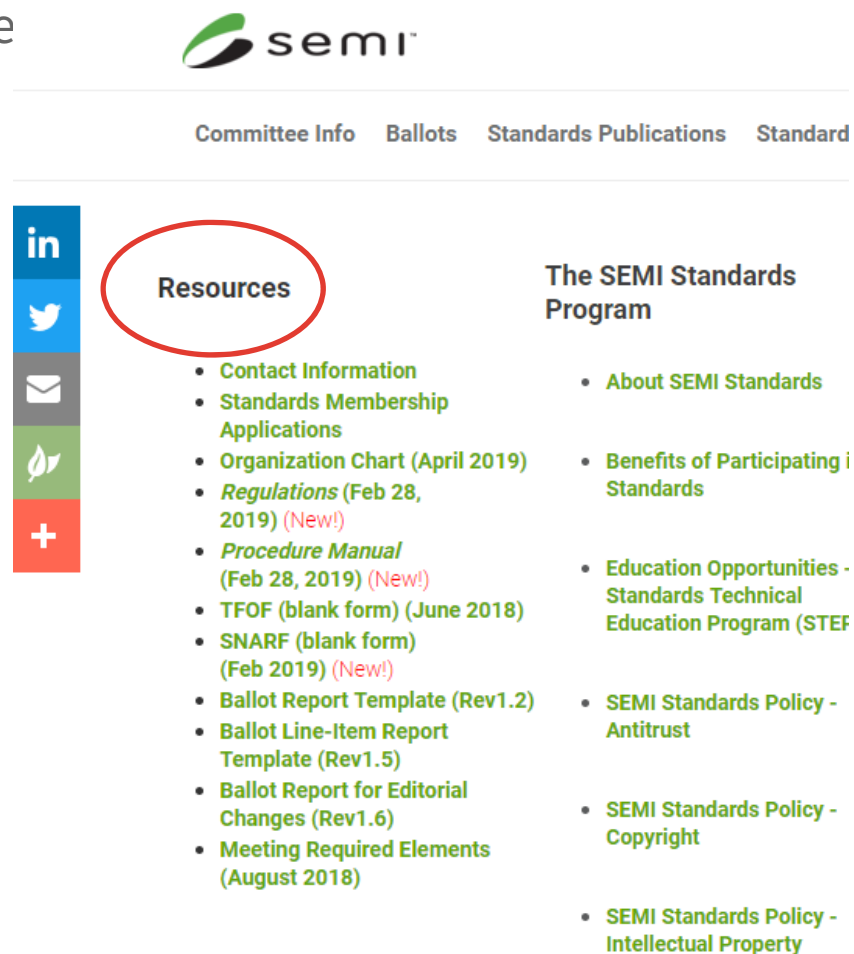


Collaboration Community

- [Connected@SEMI](#)
The secure online, interactive platform for Committee and Task Force Communities
- [Instructions for Program Member](#)
Detailed instructions on how to log in and post discussion.
- [Instructions for TF Leader/Community Admin](#)
Detailed instructions on how to add member, upload minutes, and other tasks.

New Forms, Regulations, and Procedure Manual

- *Regulations* (Feb 28, 2019)
 - Latest version clarifies procedure and trademarks
- *Procedure Manual* (Feb 28, 2019)
- SNARF (Feb 2019)
- www.semi.org/standards
 - Under Resources



semi

Committee Info Ballots Standards Publications Standard

in
Twitter
Email
RSS
+

Resources

- Contact Information
- Standards Membership Applications
- Organization Chart (April 2019)
- *Regulations* (Feb 28, 2019) (New!)
- *Procedure Manual* (Feb 28, 2019) (New!)
- TFOF (blank form) (June 2018)
- SNARF (blank form) (Feb 2019) (New!)
- Ballot Report Template (Rev1.2)
- Ballot Line-Item Report Template (Rev1.5)
- Ballot Report for Editorial Changes (Rev1.6)
- Meeting Required Elements (August 2018)

The SEMI Standards Program

- About SEMI Standards
- Benefits of Participating i Standards
- Education Opportunities - Standards Technical Education Program (STEF)
- SEMI Standards Policy - Antitrust
- SEMI Standards Policy - Copyright
- SEMI Standards Policy - Intellectual Property

Style Manual Update

- Style Manual Version 6 (March 25, 2019)
 - Additions and revisions to harmonize with updated *Regulations* and *Procedure Manual*
 - Updates
 - *Company or Organization Trademarks (Table 1, #1-24)*
 - *Active vs. Passive Voice (Table 4, #4-4)*
 - *Word Usage (Table 4, #4-5)*
 - *New Safety Guideline Conformance Notice (Table 8, #8-1)*
- www.1semi.org/standards/standardspublications
 - Under Document Authoring Tools

Global Staff Assignment - Japan

- Mizue Iwamura
 - Automation Technology
 - Information & Control
 - Facilities
 - Gases
 - Liquid Chemicals
 - Photovoltaic
 - Photovoltaic Materials
- Junko Collins
 - Compound Semiconductor Materials
 - Silicon Wafer
 - (JRSC)
- Chie Yanagisawa
 - 3D Packaging & Integration
 - EHS
 - FPD M&C
 - FPD Meteorology
 - Metrics
 - Physical Interfaces & Carriers
 - Traceability

Global Staff Assignment - North America

- Kevin Nguyen
 - Compound Semiconductor Materials
 - EHS
 - Microlithography
 - Photovoltaic
 - Photovoltaic Materials
 - Silicon Wafer
- Inna Skvortsova
 - Automated Test Equipment
 - HB-LED
 - Information & Control
 - Liquid Chemicals
 - Metrics
 - Traceability
- Laura Nguyen
 - 3D Packaging & Integration
 - Facilities
 - Gases
 - MEMS / NEMS
 - Physical Interfaces & Carriers

Global Staff Assignment – Other regions

- China
 - Isadra Jin
 - HB-LED
 - PV
 - PV Materials
- EU
 - James Amano and Kevin Nguyen
 - Automation Technology
 - Compound Semiconductor Materials
 - Gases
 - Information & Control
 - Liquid Chemicals
 - Metrics
 - Physical Interfaces & Carriers
 - PV Materials
 - Silicon Wafer
- Korea
 - Natalie Shim
 - Facilities
 - FPD Metrology
 - FPD Materials & Components
 - Information & Control
- Taiwan
 - Dean Chang, Tiffany Huang
 - 3D Packaging & Integration
 - Automation Technology
 - EHS
 - FPD Metrology
 - Information & Control
 - PV

Global Staff Assignment - International

- James Amamo
 - ISC
- Kevin Nguyen
 - Regulation
 - Audit & Review

A large red rectangular area with a decorative border on the left and top edges. Inside the red area, there are several semi-transparent hexagonal shapes of varying sizes and shades of red, creating a layered, geometric pattern.

Thank you

Back Up

Reg Subcommittee

- 規約およびPMの改訂
 - 2019年2月28日に公表
 - 2019年北米地区スタンダード委員会より適用となる

REG SC

改訂の背景

- Trademark関連： § 16の前回改訂に対する矛盾点を修正
 - § 1.5.11: harmonized with standard practice in *PM* related to subheadings for SDOs
 - § 8.8 and ¶ 9.2.5.1.1.3 harmonized with § 16
 - § 16.4.4 revised for further clarification for trademark procedures
- SEMIのリーガルカウンシルによるIP関連のセクションの見直しで生じた懸念の解決
 - “Use of trademark in Standard Document” might be confusing
 - Potential of misunderstanding that reproduction of SEMI Standards in other documents such as user-supplier agreement is allowed without obtaining specific permission or license from SEMI
 - “Use of copyrighted material” might imply copyright violation

REGS

規約改訂のサマリ

- IP関連ポリシーの明確化
 - Addressed potential confusion about confidentiality of information disclosed in SEMI Standards Program
 - Improvements made in § 1.5.11 Use of Proper Names and Trademarks
 - Clarified that SEMI Standards are used by reference (SEMI's Copyright), but not by inclusion in other documents (¶ 1.5.9) in the context of the paragraph.
- Trademarkに関する § 8および § 9と § 16の矛盾修正
- LOIのアクセプタンス条件に関する確認
- 著作物および商標に適用可能な言葉の統一および手順の明確化
 - “copyrighted item(s)” is replaced with a new defined term (as defined in ¶ 4.3), and copyrighted material(s) is replaced with Copyrighted Item(s), where appropriate.
 - “use (n., v.)” or “reproduction (n.)/reproduce (v.) in the contexts of Copyrighted Items or third-party trademarks in the Standard Documents are replaced with “incorporation (n.)/ incorporate (v.).

REG SC

PM改訂のサマリ

- 規約改訂に伴う必要な変更
- Table6の「編集上の変更に該当しない項目」に例を追加
- Noticeの使用に関する説明
- “nonconforming title”を訂正するためのAppendix4の改訂およびアップデート